



Acquisition of All Shares of Yamanaka Hutech Corporation

May 16th, 2024

Executive Summary

Entry into the Deposition field, which is driving the complexity of semiconductor structures.

- YHC, which has a proven track record of in ALD materials for cutting-edge semiconductor devices, is now part of JSR Group.
- Aiming for semiconductor materials leadership, adds precursor to product portfolio
- A common culture that emphasizes innovation, technology and quality to contribute to customer value
- Strengthen YHC's product development resources and provide global sales and technical support infrastructure
- Business expansion through expansion of customer base and product expansion into new Si-based and metal-based materials

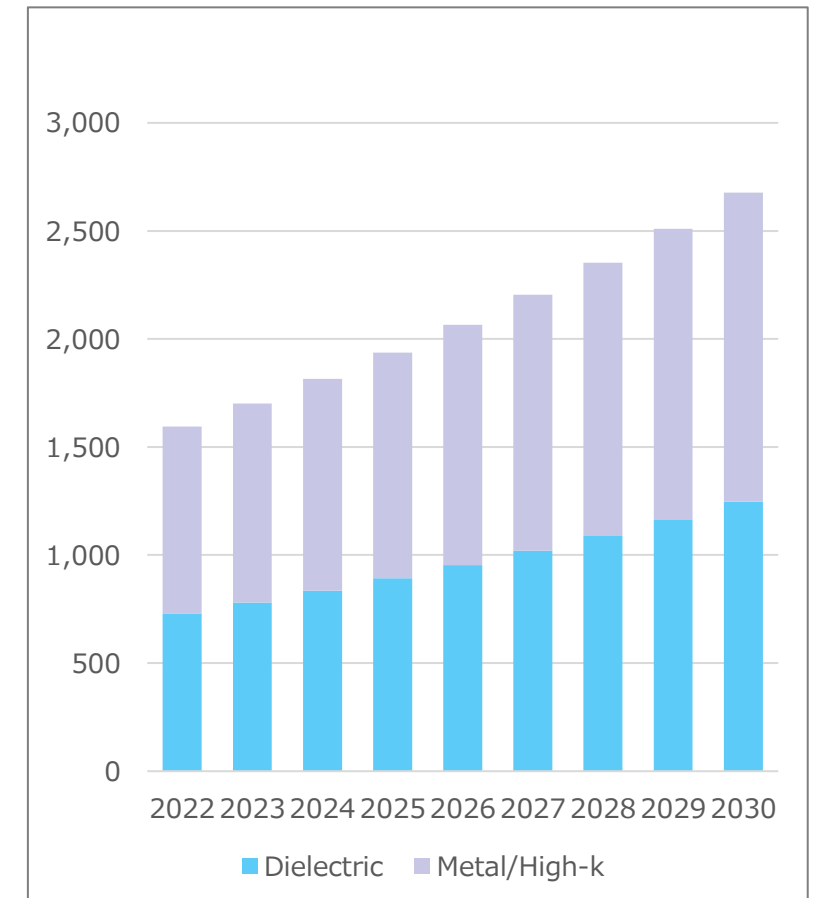
Investment Overview

Case summary	Agreement reached to acquire all shares of Yamanaka Hutech Corporation and make it a wholly owned subsidiary of JSR
Subject company	<p>Yamanaka Hewtech Corporation (President: Tsuyoshi Moriwaki)</p> <ul style="list-style-type: none"> • Manufacture and sale of high-purity chemicals for semiconductor materials, optical fiber materials, etc. • HQ: 29, Shimogamo Matsubara-cho, Sakyo-ku, Kyoto-shi, Kyoto • Established: November 1, 1967 • Number of employees: 76 (As of June 2023)
Schedule	<p>Signing: May 15, 2024</p> <p>Closing : Aug 2024 (Plan)</p>

YHC Products

Fine Chemicals	CVD materials	<ul style="list-style-type: none"> Al wiring protection film, interlayer dielectric, Low-K film and gas barrier film TEOS/TEPO/TMPO/TEB/HMDS/HMSDO, etc.
	ALD materials	<ul style="list-style-type: none"> Si-based strategic products
	Diffusion materials	<ul style="list-style-type: none"> POCl₃/BBr₃/SiCl₄/Ga-based materials, etc.
	Materials for Power Devices	
	Materials for Resist	<ul style="list-style-type: none"> Si-based strategic products
MEMS		<ul style="list-style-type: none"> Contract service processing to various MEMS sensors, inkjet, medical devices, etc.
Coatings		<ul style="list-style-type: none"> Development and sales of coatings for spray application Contract service of precision spray coatings
Silicon Glass Wafer		<ul style="list-style-type: none"> Sales of various substrates of 2-12 inch size silicon wafers and processing services for various wafers

(Reference) Estimated precursor market size (MUSD)



Device Trends and Key Technologies



□ Driving Force of Device Evolution

1. Scaling



- Contribution to miniaturization by EUV resists including metal resists and multilayer material lineup

2. Complexity



- Precursor, a key material in the deposition process responsible for structural complexity, is added to our portfolio.

3. 3D

- Heterogeneous Integration